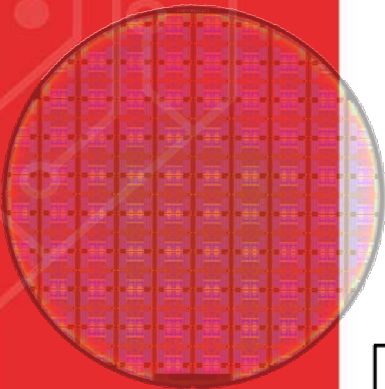
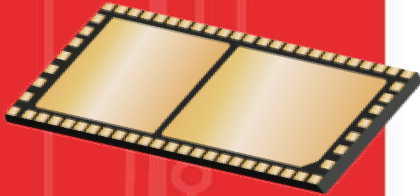




Taiwan Microelectronics Inc.



[www.taiwanmicro.com.tw](http://www.taiwanmicro.com.tw)

# TM2100/TM2110

LGA 6x16X1.3mm-62L

2.4GHz wireless Audio SiP IC

The Ginseng (XC1603) System in Package (SiP) is one of the core wireless components used for audio transmitters (Tx) and receivers (Rx) in Eleven Engineering's wireless audio platforms. This SiP is a highly integrated device that contains all of the required components for a generic RF turn-key solution except for an external antenna and reference crystal.

Eleven's proprietary adaptive frequency hopping protocol uses a narrow footprint in the 2.4 GHz band allowing seamless co-existence with other devices and offering unparalleled Quality of Service. Ginseng outputs digital audio information in I2S format. Ginseng can function as both a transmitter and receiver depending on firmware.

## Features

- Custom QFN-62 package
- Uses Eleven's XInC2 multithreaded RISC processor, specifically built for high fidelity wireless audio
- Digital I2S Audio Output
- 2.4 GHz wireless at 2.0 Mbps
- Highly customizable RF-Link for multi-purpose applications
- High RF output power (17 dBm)
- High receive sensitivity (-80 dBm @ 3% PER)
- Small form factor
- Compatible with FCC/ETSI regulations
- MSL-3, REACH/RoHS complaint

## Applications

- High resolution wireless Audio
- 1 to 4 bond system
- Very low latency

## Functional Block Diagram

